



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-30
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	LAURENT TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F722ZET6	P01A*452ESXA	A	9998	2016-08-30
	Amount	UoM	Unit type	ST ECOPACK Grade
	1315.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	20x20x1.4	144	L bend	
Comment	LQFP 144 20x20x1.4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	P01A*45ZESXA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	20.881	mg	supplier	die	Silicon (Si)	7440-21-3		18.391	mg	880753	13986
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0.068	mg	3257	52
Die or Dies				supplier	metallization	Copper (Cu)	7440-50-8		0.443	mg	21215	337
Die or Dies				supplier	metallization	Tantalum (Ta)	7440-25-7		1.577	mg	75523	1199
Die or Dies				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	48	1
Die or Dies				supplier	metallization	Tungsten (W)	7440-33-7		0.199	mg	9530	151
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.052	mg	2490	40
Die or Dies				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.150	mg	7184	114
LEADFRAME (MHT- C194 PPF)	Other inorganic materials	256.512	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		240.882	mg	939067	183180
LEADFRAME (MHT- C194 PPF)				supplier	ALLOY	Iron (Fe)	7439-89-6		5.932	mg	23126	4511
LEADFRAME (MHT- C194 PPF)				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.297	mg	1158	226
LEADFRAME (MHT- C194 PPF)				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.074	mg	288	56
LEADFRAME (MHT- C194 PPF)				supplier	COATING	Nickel (Ni)	7440-02-0		9.042	mg	35250	6876
LEADFRAME (MHT- C194 PPF)				supplier	COATING	Palladium (Pd)	7440-05-3		0.192	mg	749	146
LEADFRAME (MHT- C194 PPF)				supplier	COATING	Gold (Au)	7440-57-5		0.093	mg	363	71
DIE ATTACH (CRM - 1076YB)	Other inorganic materials	1.993	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.100	mg	50176	76
DIE ATTACH (CRM - 1076YB)				supplier	GLUE	Epoxy resin B	Trade secret		0.149	mg	74762	113
DIE ATTACH (CRM - 1076YB)				supplier	GLUE	Silver(Ag)	7440-22-4		1.395	mg	699950	1061
DIE ATTACH (CRM - 1076YB)				supplier	GLUE	Silica	Trade secret		0.299	mg	150025	227
DIE ATTACH (CRM - 1076YB)				supplier	GLUE	Hardener	Trade secret		0.050	mg	25088	38
BONDING WIRE (Heraeus - HTS Au w)	Other inorganic materials	2.518	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		2.493	mg	990071	1896
BONDING WIRE (Heraeus - HTS Au w)				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.025	mg	9929	19
ENCAPSULATION (Sumitomo -G631H)	Other inorganic materials	1032.007	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		104.035	mg	100808	79114
ENCAPSULATION (Sumitomo -G631H)				supplier	MOLDING COMPOUND	Silica fused (SiO3)	60676-86-0		873.422	mg	846333	664199
ENCAPSULATION (Sumitomo -G631H)				supplier	MOLDING COMPOUND	Phenol Resin	Trade secret		49.348	mg	47818	37527
ENCAPSULATION (Sumitomo -G631H)				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		5.202	mg	5041	3956
FINISHING - (MHT - PPF)	Other inorganic materials	1.089	mg	supplier	CONNECTION COATING	Nickel (Ni)	7440-02-0		1.061	mg	974288	807
FINISHING - (MHT - PPF)				supplier	CONNECTION COATING	Palladium (Pd)	7440-05-3		0.023	mg	21120	17
FINISHING - (MHT - PPF)				supplier	CONNECTION COATING	Gold (Au)	7440-31-5		0.005	mg	4591	4